ABSTRACT OF THE DISCLOSURE

A polishing material which controls a polishing rate of a silicon surface is provided. A polishing material including abrasive grains and a compound represented by a Formula (1).

$R\text{-}O\text{-}(AO)_n\text{-}H$ Formula (1)

In the Formula (1), R is an organic group including a conjugated system and may include a heteroatom in a carbon skeleton, and $C1/(C1 + C2) \geq 0.4$ holds, where C1 is the number of atoms constituting the conjugated system and C2 is the number of atoms not constituting the conjugated system among atoms constituting the carbon skeleton,

AO represents an oxyalkylene group, and a plurality of the AOs may be the same as or different from each other, and

n is an integer of 2 to 200.

FIG. 1A